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Attorney Docket No. 102423-108
U.S. Serial No. 10/561,381
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AMENDMENTS TO THE SPECIFICATION

In the Specification:

Please replace Paragraph [0003] beginning at page 1, line 11, with the following rewritten paragraph:

This invention relates to a lead frame for [a] molded plastic packages of the type that encapsulates one or more semiconductor devices. More particularly, the lead frame is formed by a sequential metal removal process that selectively patterns external lead ends, routing circuits and internal lead ends from a single electrically conductive substrate.

Please replace Paragraph [0010] beginning at page 3, line 1, with the following rewritten paragraph:

Another method for the manufacture of a QFN package is disclosed in commonly owned United States patent application serial number ~~10/134,882~~ that was filed on April 29, 2002 Patent Number 6,812,552 and is incorporated by reference in its entirety herein. ~~Serial number 10/134,882~~ The application that issued as U.S. Patent No. 6,812,552 was published on October 30, 2003 as United States Patent Application Publication US 2003/0203539 A1.